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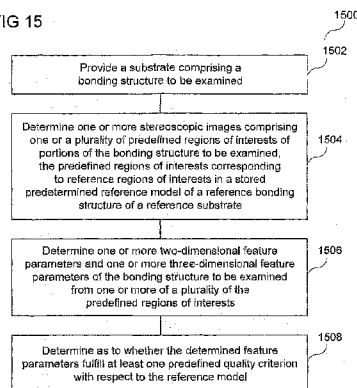
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(54) Title: METHODS FOR EXAMINING A BONDING STRUCTURE OF A SUBSTRATE AND BONDING STRUCTURE INSPECTION DEVICES

FIG 15



(57) Abstract: In an embodiment, a method for examining a bonding structure of a substrate may be provided. The method may include: providing a substrate including a bonding structure to be examined; determining one or more stereoscopic images including one or a plurality of predefined regions of interests of portions of the bonding structure to be examined, the predefined regions of interests corresponding to reference regions of interests in a stored predetermined reference model of a reference bonding structure of a reference substrate; determining one or more two-dimensional feature parameters and one or more three-dimensional feature parameters of the bonding structure to be examined from one or more of a plurality of the predefined regions of interests; and determining as to whether the determined feature parameters fulfill at least one predefined quality criterion with respect to the reference model.